DECLARATION AND POWER OF ATTORNEY FOR UNITED STATES PATENT APPLICATION

English Language Declaration

As a below named inventor, I hereby declare that:

My residence, mailing address and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled:

BIOABSORBABLE PLUG IMPLANTS AND METHOD FOR BONE TISSUE REGENERATION

the specification	n of which	ı:	
(check one)	[X] is	s attached hereto.	
	[] v	vas filed ona	s U.S. Application Serial No.
•	a	and was amended on	(if applicable).
		reviewed and understand the content y any amendment referred to above.	s of the above identified specification, including
-	al to pater	ntability as defined in Title 37, Code	and Trademark Office all information known to of Federal Regulations Code of Federal
above invention	, and whi	• • • • • • • • • • • • • • • • • • • •	lo not claim priority, but which relates to the 's certificate or PCT International application has iority is claimed.
Number	Cou	intry	Day/Month/Year Filed
Number	Coı	ıntry	Day/Month/Year Filed
365(b) of any fo	oreign appoplication	lication(s) for patent or inventor's cowhich designated at least one countr	States Code, Section 119(a)-(d) or Section ertificate, or Section 365(a) of any PCT y other than the United States, listed below and
Prior Foreign A	pplication	n(s):	
Number	- ·	Country	Day/Month/Year Filed
Number		Country	Day/Month/Year Filed
			,

I hereby claim the benefit under 35 U.S.C. Section 119(e) of any United States provisional application(s) listed below:

21 November 2003 (21.11.2003)		
ng Date)		
ng Date)		
ir		

I hereby claim the benefit under 35 U.S.C. Section 120 of any United States application(s), or Section 365(c) of any PCT International application designating the United States, listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States or PCT International application in the manner provided by the first paragraph of 35 U.S.C. Section 112, I acknowledge the duty to disclose to the United States Patent and Trademark Office all information known to me to be material to patentability as defined in Title 37, C.F.R., Section 1.56 which became available between the filing date of the prior application and the national or PCT International filing date of this application.

(Application Serial No.)	(Filing Date)	(Status) (Patented, pending, abandoned)
PCT/SG2004/000380	22 November 2004	Pending
(Application Serial No.)	(Filing Date)	(Status) (Patented, pending, abandoned)
(Application Serial No.)	(Filing Date)	(Status) (Patented, pending, abandoned)

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

POWER OF ATTORNEY: As a named inventor, I hereby appoint the following attorney(s) and/or agent(s) to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith:

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Docket No. 2597.004
(FP3037/GM)

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